CLAIMS

[Claim 1]

An anisotropic conductive film comprising an insulating adhesive layer and conductive particles regularly arranged in the insulating adhesive layer as viewed in a plan view, wherein a conductive particle diameter is 10 μm or more, the film has a thickness of 1 or more times and 3.5 or less times the conductive particle diameter, positions of the conductive particles are varied in a thickness direction of the film within a variation range of less than 10% of the conductive particle diameter, and a difference between maximum and minimum values of particle densities, as viewed in a plan view, measured at ten regions which each have an area of 1 mm × 1 mm and are extracted in a longitudinal direction of the anisotropic conductive film is less than 20% of an average of the particle densities at the respective region.

[Claim 2]

The anisotropic conductive film according to claim 1, wherein the thickness of the film is 1 or more times and 2.5 or less times the conductive particle diameter.

[Claim 3]

The anisotropic conductive film according to claim 1, wherein the thickness of the film is 1 or more times and 1.7 or less times the conductive particle diameter.

[Claim 4]

The anisotropic conductive film according to any one of claims 1 to 3, wherein a distance between one surface of the anisotropic conductive film and each conductive particle is 10% or more of the conductive particle diameter.

[Claim 5]

The anisotropic conductive film according to any one of claims 1 to 4, wherein the conductive particles are disposed to be flush with, or close to, at least one surface of the anisotropic conductive film.

[Claim 6]

The anisotropic conductive film according to any one of claims 1 to 5, wherein a particle density of the conductive particles is 20 to 2,000 particles/mm^2.

[Claim 7]

The anisotropic conductive film according to any one of claims 1 to 6, wherein the insulating adhesive layer is a single layer.

[Claim 8]

The anisotropic conductive film according to any one of claims 1 to 7, wherein the insulating adhesive layer contains a polymerizable resin.

[Claim 9]

The anisotropic conductive film according to any one of claims 1 to 8, wherein an alignment mark for an

electronic component to be anisotropically, conductively connected is formed by a disposition of particles for an alignment mark.

[Claim 10]

A connection structure wherein a first electronic component and a second electronic component are anisotropically, conductively connected by the anisotropic conductive film according to any one of claims 1 to 9.

[Claim 11]

The connection structure according to claim 10, wherein the first electronic component is a wiring substrate and the second electronic component is a camera module.

[Claim 12]

A method for manufacturing a connection structure comprising anisotropically, conductively connecting a first electronic component and a second electronic component by the anisotropic conductive film according to any one of claims 1 to 9.

[Claim 13]

A connection method comprising a step of interposing the anisotropic conductive film according to any one of claims 1 to 9 between a first electronic component and a second electronic component and heating and pressurizing them.